Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
Li	1	("5869354").PN.	USPAT	OR	OFF	2006/04/02 16:09
S1	5606	((438/33) or (438/106) or (438/113) or (438/114) or (438/458) or (438/460) or (438/463) or (438/465)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/03 22:15
S2	6481	((438/33) or (438/106) or (438/113) or (438/114) or (438/458) or (438/460) or (438/463) or (438/464) or (438/465)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/10 15:39
S3	337	S1 and (singulat\$3 same wafer\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/03 22:50
S4	66	S3 and (adhesive near2 tape)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/10 15:42
S5	14	(("3976288") or ("4925515") or ("5460703") or ("5705016") or ("6039830") or ("6150240") or ("6245646") or ("6344402") or ("6498074") or ("6251488") or ("6259962") or ("6268584") or ("6391251") or ("6562661")).PN.	US-PGPUB; USPAT	OR	OFF	2005/05/24 15:38
S6	1	("20050064683").PN.	US-PGPUB; USPAT	OR	OFF	2005/05/24 15:38
S7	6608	((438/33) or (438/106) or (438/113) or (438/114) or (438/458) or (438/460) or (438/463) or (438/464) or (438/465)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/24 16:39
S8	11	S7 and ((wafer near size\$1) same ("300 mm"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 16:40

S9	6608	((438/33) or (438/106) or (438/113) or (438/114) or (438/458) or (438/460) or (438/463) or (438/464) or (438/465)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/24 16:54
S10	13	S9 and (without near ((film near frame) or carrier))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 16:58
S11	0	(without near ((film near frame) or carrier)) same wafer\$1 same singulat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 16:58
S12	12	(without near ((film near frame) or carrier)) and (wafer\$1 same singulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:11
S13	2821	(wafer\$1 same singulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/24 17:06
S14	18	S13 and (without near ((film near frame) or frame or carrier))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:03
S15	33526	(without near ((film near frame) or frame or carrier))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:02
S16	480	S15 and (wafer\$1 same (mount\$3 or hold\$3 or clamp\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:56

S17	11	S16 and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:04
S18	12	S16 and singulat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:06
S19	1	S18 not S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:09
S20	1512	(remov\$3 near (ic\$1 or die\$1 or (integrated adj circuit\$1))) same (substrate or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/29 11:47
S21	20	S20 and (without near ((film near frame) or carrier))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:17
S22	14	S21 not S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:12
S23	1143	S20 and (without or without near us\$3 or ("not" near us\$3) near ((film near frame) or carrier or (film adj frame adj carrier)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:19
524	1143	S20 and (without or (without near us\$3) or ("not" near us\$3) near ((film near frame) or carrier or (film adj frame adj carrier)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:04

S25	138	S24 and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:20
S26	23	S25 and S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24:17:20
S27	149	S13 same (wafer\$1 same (hold\$3 or clamp\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:57
S28	19	S20 and S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 17:58
S29	26341	(without near ((film near frame) or frame or carrierr or ring))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:09
S30	1	S29 same S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:04
S31	6805216	(without or (without near us\$3) or ("not" near us\$3) near (frame or carrier or ring))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:06
S32	316	S31 same S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24:18:06

S33	0	S13 same (without near ring)	US-PGPUB;	OR	ON	2005/05/24 18:10
		· · · · · · · · · · · · · · · · · · ·	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB			
S34	4	S13 and(without near ring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ÖR	ON	2005/05/24 18:10
S35	4	S13 and (without near ring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:11
S36	89	S13 and (without same ring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:19
S37	3	(clamp\$3 near wafer) same (wafer same singulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:30
538	1243	((pick near place) near (apparatus\$1 or machine\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:31
S39	5	S38 and (clamp\$3 near wafer\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:36
540	28	S38 and ((clamp\$3 or hold\$3) near wafer\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:42

		LAST Seat		•		
S41	23	S40 not S39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:36
S42	2	S38 and ((jig or clamp) near wafer\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24:18:42
S43	0	S38 and (jig near wafer\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 18:42
S44	4	"6524881"	USPAT	OR	OFF	2005/05/24 20:18
S45	1	("5869354").PN.	USPAT	OR	OFF	2005/11/10 15:38
S46	7038	((438/33) or (438/106) or (438/113) or (438/114) or (438/458) or (438/460) or (438/463) or (438/464) or (438/465)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/28 16:55
S47	697	S46 and ((grip\$4 or clamp\$3 or hold\$3) near5 (semiconductor or wafer\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/10 16:12
S48	201	S47 and (adhesive near3 tap\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/10 16:10
S49	52	S48 and ((remov\$3 or singulat\$3) near3 (ic\$1 or die\$1 or (integrated adj circuit\$1))) same (substrate or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/10 16:11
S50	59	S48 and ((remov\$3 or singulat\$3) near3 (component\$1 or ic\$1 or die\$1 or (integrated adj circuit\$1))) same (substrate or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/10 15:47

S51	7038	((438/33) or (438/106) or (438/113) or (438/114) or (438/458) or (438/460) or (438/463) or (438/464) or (438/465)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/12 15:34
S52	5114	((grip\$4 or clamp\$3) near3 wafer\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/12 15:35
S53	13304	S51 snf S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/12 15:35
S54	58	S51 and S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/12 15:41
S55	3	S54 and (pick adj plac\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/12 15:43
S56	93	S52 and (pick adj plac\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/12 15:43
S57	90	S56 not S55	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/12 15:44
S58	64	(("EBR" or (edge adj bead adj ring)) near3 wafer\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/12 16:15

S59	4	S51 and S58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/12 16:13
S60	15	("20030096507" "20040110010" "5164815" "5313102" "5476566" "5583372" "6027659" "6184064" "6235387" "6245677" "6258198" "6279976" "6403449" "6506681" "6534419").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/12 16:53
S61	0	("6940181").URPN.	USPAT	OR	OFF	2005/11/12 16:54
S62	1	("4702592").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/12 16:58
S63	7292	((438/33) or (438/106) or (438/113) or (438/114) or (438/458) or (438/460) or (438/463) or (438/464) or (438/465)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/27 17:01
S64	1	S63 and (singula\$4 near10 (("without" or (("not" or "no") adj us\$3)) near2 (film adj frame\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:03
S65	1	S63 and (singula\$4 near10 (("without" or (("not" or "no") adj us\$3)) near10 (film adj frame\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:03
S66	2	(singula\$4 near10 (("without" or (("not" or "no") adj us\$3)) near10 (film adj frame\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:06
S67	5	S63 and ((singula\$4 or dic\$3 or saw\$3 or ablat\$3 or cut\$4 or separat\$3) near10 (("without" or (("not" or "no") adj us\$3)) near10 (film adj frame\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:10

S68	32	((singula\$4 or dic\$3 or saw\$3 or ablat\$3 or cut\$4 or separat\$3) near10 (("without" or (("not" or "no") adj us\$3)) near10 (film adj frame\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:14
S69	64	((singula\$4 or dic\$3 or saw\$3 or ablat\$3 or cut\$4 or separat\$3) same (("without" or (("not" or "no") adj us\$3)) near10 (film adj frame\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/29 15:58
S70	32	S69 not S68	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:15
S71	17715	((singula\$4 or dic\$3 or saw\$3 or ablat\$3 or cut\$4 or separat\$3) same (("without" or (("not" or "no") adj us\$3)) near10 ((film adj frame\$1) or frame\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/29 11:49
S72	17782	((singula\$4 or dic\$3 or saw\$3 or ablat\$3 or cut\$4 or separat\$3) same (("without" or (("not" or "no") adj us\$3)) near10 ((film adj frame\$1) or frame\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:48
S73	7371	((438/33) or (438/106) or (438/113) or (438/114) or (438/458) or (438/460) or (438/463) or (438/464) or (438/465)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/27 17:01
S74	58	S72 and S73	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 17:02
S75	1	("5803797"):PN.	USPAT	OR	OFF	2006/03/29 11:42
S76	595	porous near10 chuck	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/29 11:46

S77	425	S76 and (ic\$1 or die\$1 or (integrated adj circuit\$1) or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT;	OR	ON	2006/03/29 11:48
S78	341	S77 and (singula\$4 or dic\$3 or saw\$3 or ablat\$3 or cut\$4 or separat\$3)	IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO;	OR	ON	2006/03/29 11:50
			DERWENT; IBM_TDB			
S79	16	("3004766" "3690780" "3809050" "3811182" "3976288" "4138304" "4521995" "4597228" "4625463" "4808406" "5029418" "5445559" "5451549" "5527744" "5605489").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/29 14:08
S80	23	("5803797").URPN.	USPAT	OR	OFF	2006/03/29 14:12
S81	20	("3004766" "3690780" "3809050" "3811182" "3976288" "4138304" "4521995" "4597228" "4625463" "4808046" "4808406" "5029418" "5203547" "5410791" "5445559" "5451549" "5527744" "5605489"	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/29 14:18
S82	11	("20030051338" "20030060025" "3811182" "4685363" "5803797" "6024631" "6165232" "6187654" "6239380" "6255196" "6448156").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/29 15:51
S83	0	("6683378").URPN.	USPAT	OR	OFF	2006/03/29 15:55
S84	287855	(singula\$4 or dic\$3 or saw\$3 or ablat\$3 or cut\$4 or separat\$3) with (adhesive or coat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 16:53
S85	232995	S84 and @pd<"20030919"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/29 16:13

S86	23029	(singula\$4 or dic\$3 or saw\$3 or ablat\$3 or cut\$4 or separat\$3) with ((adhesive or coat\$3) with tap\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/29 16:12
S87	18732	S86 and @pd<"20030919"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 17:15
S88	4741	S87 and (polymer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/29 16:18
S89	494	S88 and ((back adj grind\$3) or backgrind\$3 or ((thin\$4 or grind\$3) with (substrate or wafer)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/29 16:20
S90	1356	((singula\$4 or dic\$3 or saw\$3 or ablat\$3 or cut\$4 or separat\$3) with tape) same ((remov\$3 or (pick\$3 with place)) with (ic\$1 or die\$1 or (integrated adj circuit\$1) or semiconductor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 17:03
S91	960	S90 and @pd<"20030919"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 17:16